COMBINED DECLARATION AND POWER OF ATTORNEY

As the below named inventor, I hereby declare that:

the specification of which

X is attached hereto.

My residence, post office address and citizenship are as stated below next to my name and that I believe I am an original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

LOW TEMPERATURE POLYSILICON THIN FILM TRANSISTOR AND METHOD OF FORMING POLYSILICON LAYER OF SAME

	was filed on							
			and was amended on	and was amended on				
app app fore	cification, including t I acknowledge the lication in accordand I hereby claim fore lication(s) for paten	the claims, as amended to duty to disclose information in the second to the claims, as amended to the claims of the control of the claims of t	nd understand the content d by any amendment referre rmation which is material to of Federal Regulations, § 1. der Title 35, United States C ate listed below and have ificate having a filing date be	d to above. the patenta 56(a). code, § 119 also identific	ability of this of any foreign ed below any			
	Number	Country	Date Filed(yyyy/mm/dd)	Yes	No			
	92107490	Taiwan, R.O.C.	ı, R.O.C. 2003/4/2					
I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith: Belinda Lee (Reg. No. 46,863) Jiawei Huang (Reg. No. 43,330) Charles C.H. Wu (Reg. No. 39,081)								
:	SEND CORRESPOR	NDENCE TO:		DIRECT TELEPHONE CALLS TO: (Name and telephone number)				
		800	fice Belind	la Lee				

COMBINED DECLARATION AND POWER OF ATTORNEY CONTINUED

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patents issued thereon.

Signature: _	Peng	Chia-7	len	Date:_	July	18,	2003
Sole or First	Joint Inven	tor: Chia-Tien Pe	eng				
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Residence a	ind Post Of		. 10, Alley 9, iwan, R.O.C.		Paiti St.,	Chupe	i City, Hsinchu Hsien,
Signature: _	Hua	m-Chao	Wn	Date:_	July	18,	2003
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